



### **DMP1018UCB9**

#### P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>DSS</sub>	R <sub>DS(ON)</sub>	Qg	Q <sub>gd</sub>	l <sub>D</sub>
-12V	12mΩ	4.9nC	1.1nC	-7.6A

Typ. @  $V_{GS} = -4.5V$ ,  $T_A = +25$ °C

## **Description**

This 1st generation Lateral MOSFET (LD-MOS) is engineered to minimize on-state losses and switch ultra-fast, making it ideal for high efficiency power transfer. Using Chip-Scale Package (CSP) to increase power density by combining low thermal impedance with minimal RDS(ON) per footprint area.

### **Applications**

- DC-DC converters
- Battery management
- · Load switches

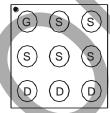
### **Features**

- LD-MOS Technology with the Lowest Figure of Merit:  $R_{DS(ON)} = 12 m\Omega \text{ to Minimize On-State Losses}$   $Q_g = 4.9 nC \text{ for Ultra-Fast Switching}$
- V<sub>GS(TH)</sub> = -0.8V Typ. for a Low Turn-On Potential
- CSP with Footprint 1.5mm x 1.5mm
- Height = 0.62mm for Low Profile
- ESD = 3kV HBM Protection of Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Qsuffix) part. A listing can be found at <a href="https://www.diodes.com/products/automotive/automotive-products/">https://www.diodes.com/products/automotive/automotive-products/</a>
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.
   <a href="https://www.diodes.com/quality/product-definitions/">https://www.diodes.com/quality/product-definitions/</a>

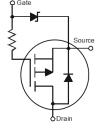
### **Mechanical Data**

- Package: U-WLB1515-9
- Terminal Connections: See Diagram Below





Top-View Pin Configuration



**Equivalent Circuit** 

## Ordering Information (Note 4)

			Pag	kina
Part Number		Package	Fac	king
T art Humber		1 ackage	Qty.	Carrier
DMP1018UCB9-7		U-WLB1515-9	3,000	Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**

● EW YM

EW = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: J = 2022) M or  $\overline{M}$  = Month (ex: 9 = September)

Date Code Key

Downloaded from **Arrow.com**.

Date Code												
Year	2012		2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Z		J	K	L	M	N	0	Р	R	S	Т
NA (1)		F-1-	NA	A		1 1	11	A	0	0-1	N	<b>D</b>
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V <sub>DSS</sub>	-12	V	
Gate-Source Voltage		Vgss	-6	V	
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	lo	-7.6 -6.0	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V	lo	-5.5 -4.3	А		
Pulsed Drain Current (Pulse Duration 10µs, Duty 0	Cycle ≤ 1%	)	I <sub>DM</sub>	-60	Α

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P <sub>D</sub>	1.0	W
Total Power Dissipation (Note 6)	PD	1.8	W
Thermal Resistance, Junction to Ambient (Note 5)	Reja	126.8	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>0JA</sub>	69	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

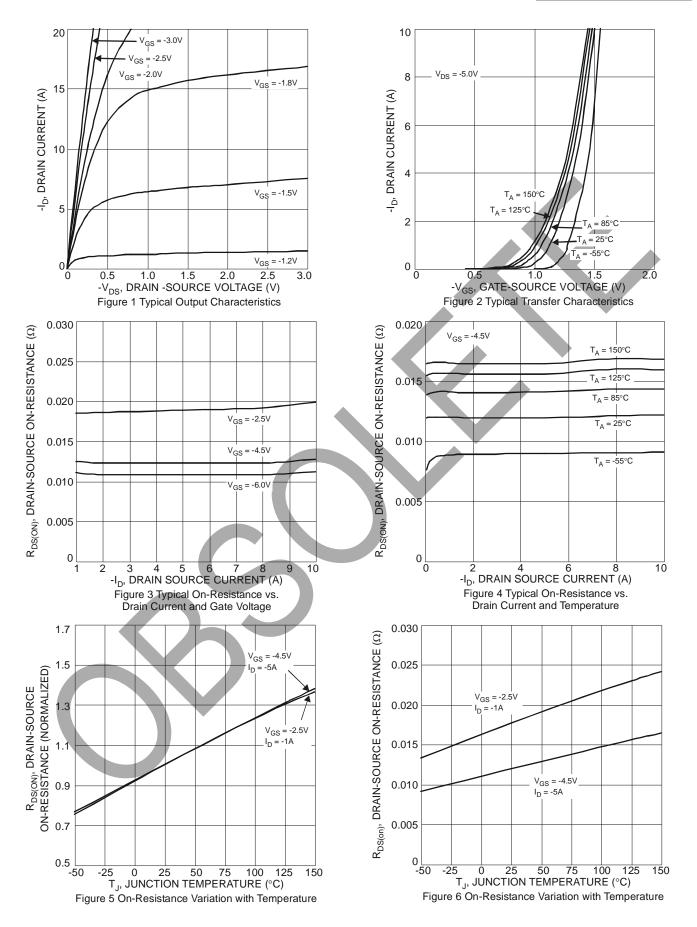
## Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BVDSS	-12	_		V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current @Tc = +25°C	loss	7		-1	μA	V <sub>DS</sub> = -9.6V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	1		-100	nA	$V_{GS} = -6.0V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	-0.8	-1.3	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$
Static Drain-Source On-Resistance	Dagger		12	18	mΩ	$V_{GS} = -4.5V, I_{D} = -2A$
Static Dialii-Source Off-Resistance	RDS(ON)	_	15	22	1112.2	Vgs = -2.5V, ID = -2A
Forward Transfer Admittance	Y <sub>fs</sub>	-	5.5	_	S	$V_{DS} = -6V, I_{D} = -2A$
Diode Forward Voltage (Note 6)	VsD		-0.7	-1	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = -2A
Reverse Recovery Charge	Qrr	_	30.2	_	nC	$V_{dd} = -5V, I_F = -2A,$
Reverse Recovery Time	t <sub>rr</sub>	_	71.4	_	ns	di/dt = 200A/µs
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C <sub>iss</sub>	_	457	_	pF	., ., ., ., .,
Output Capacitance	Coss	_	272	_	pF	V <sub>DS</sub> = -6V, V <sub>GS</sub> = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	120	_	pF	1 - 1.000112
Series Gate Resistance	Rg	_	21.23	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1.0MHz$
Total Gate Charge (-4.5V)	Qg	_	4.9	_	nC	\\ 45\\\\ 6\\
Gate-Source Charge	Qgs	_	0.6	_	nC	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -6V, I <sub>D</sub> = -2A
Gate-Drain Charge	$Q_{gd}$	_	1.1	_	nC	ID = -2A
Turn-On Delay Time	t <sub>D(on)</sub>	_	4.45	_	ns	
Turn-On Rise Time	tr	_	12	_	ns	$V_{DD} = -6V, V_{GS} = -4.5V,$
Turn-Off Delay Time	t <sub>D(off)</sub>	_	100	_	ns	$I_{DS} = -2A$ , $R_G = 2\Omega$
Turn-Off Fall Time	tf	_	93	_	ns	]

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout.
- S. Device mounted on FR4 material with 1inch² (6.45cm²), 2oz (0.071mm thick) Cu.
   Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to production testing.







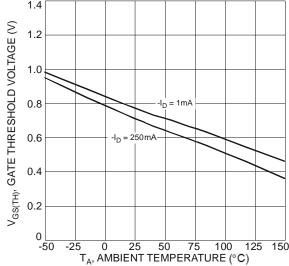
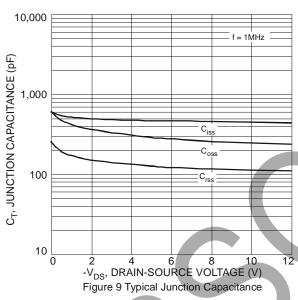
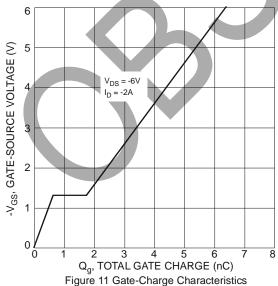
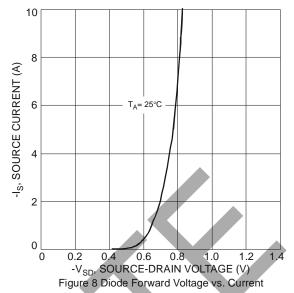


Figure 7 Gate Threshold Variation vs. Ambient Temperature







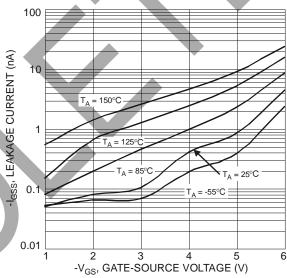
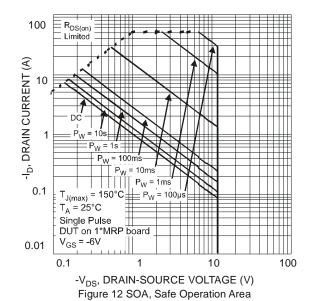
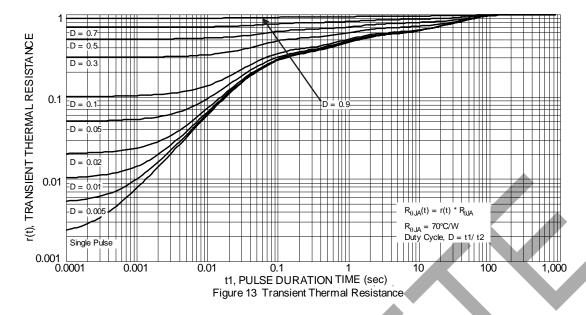


Figure 10 Typical Gate-Source Leakage Current vs. Voltage





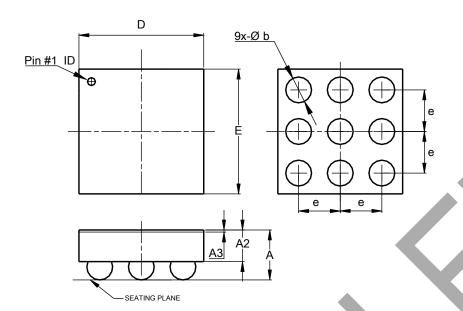




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-WLB1515-9

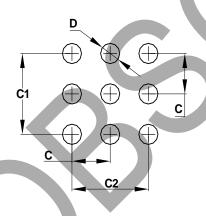


U-WLB1515-9						
Dim	Min	Max	Тур			
Α	ı	0.62				
A2 _	į	0.36	0.36			
A3	0.020	0.030	0.025			
b	0.27	0.37	0.32			
D	1.47	1.50	1.49			
Ę	1.47	1.50	1.49			
е			0.50			
All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-WLB1515-9



Dimensions	Value (in mm)
С	0.50
C1	1.00
C2	1.00
	0.25



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